

Title (en)

METHOD FOR TREATING THE SURFACE OF A WAFER

Title (de)

VERFAHREN ZUR BEHANDLUNG DER OBERFLÄCHE EINES WAFERS

Title (fr)

PROCEDE DE TRAITEMENT D'UNE SURFACE DE PLAQUETTE

Publication

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Application

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Priority

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Abstract (en)

[origin: US2006141746A1] The invention concerns a method of treating one or both bonding surfaces of first and second substrates and in particular, the surfaces of donor and receiver wafers that are intended to be bonded together. A simultaneous cleaning and activation step is carried out immediately prior to bonding the wafers together, by applying to one or both bonding surfaces an activation solution of ammonia (NH₄OH) in water, preferably deionized, at a concentration by weight in the range from about 0.05% to 2%. The method is applicable to fabricating structures used in the optics, electronics, or optoelectronics fields.

IPC 8 full level

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